**Features** 



# Low-Jitter, Wide Frequency Range, Programmable Clock Generator with 10 Outputs

### **General Description**

The MAX3639 is a highly flexible, precision phase-locked loop (PLL) clock generator optimized for the next generation of network equipment that demands low-jitter clock generation and distribution for robust high-speed data transmission. The device features subpicosecond jitter generation, excellent power-supply noise rejection, and pin-programmable LVDS/LVPECL output interfaces. The MAX3639 provides nine differential outputs and one LVCMOS output, divided into three banks. The frequency and output interface of each output bank can be individually programmed, making this device an ideal replacement for multiple crystal oscillators and clock distribution ICs on a system board, saving cost and space.

This 3.3V IC is available in a 7mm x 7mm, 48-pin TQFN package and operates from -40°C to +85°C.

### \_Applications

Ethernet Switch/Router
Wireless Base Station
SONET/SDH Line Cards

PCIe<sup>®</sup>, Network Processors

Fibre Channel SAN

Typical Application Circuits and Pin Configuration appear at end of data sheet.

#### ♦ Inputs

Crystal Interface: 18MHz to 33.5MHz LVCMOS Input: 15MHz to 160MHz Differential Input: 15MHz to 350MHz

Outputs

LVCMOS Output: Up to 160MHz LVPECL/LVDS Outputs: Up to 800MHz

- Three Individual Output Banks Pin-Programmable Dividers Pin-Programmable Output Interface
- ♦ Wide VCO Tuning Range (3.60GHz to 4.025GHz)
- Low Phase Jitter

   0.34psrms (12kHz to 20MHz)
   0.14psrms (1.875MHz to 20MHz)
- ◆ Excellent Power-Supply Noise Rejection
- -40°C to +85°C Operating Temperature Range
- → +3.3V Supply

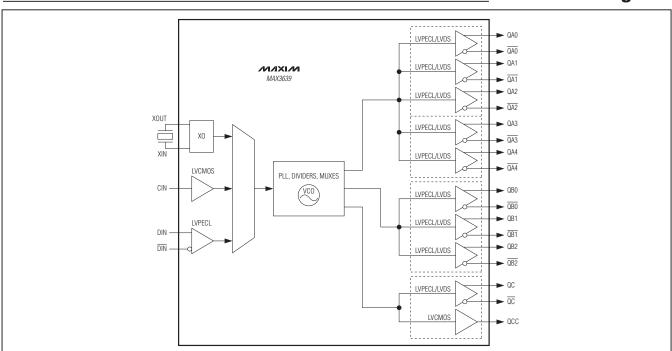
#### Ordering Information

PART	TEMP RANGE	PIN-PACKAGE
MAX3639ETM+	-40°C to +85°C	48 TQFN-EP*

+Denotes a lead(Pb)-free/RoHS-compliant package.

\*EP = Exposed pad.

### **Functional Diagram**



PCIe is a registered trademark of PCI-SIG Corp.

Maxim Integrated Products 1

### **ABSOLUTE MAXIMUM RATINGS**

Supply Voltage Range (VCC, VCCA, VCCQA, VCCQB, VCCQC, VCCQCC)0.3V to +4.0V
Voltage Range at CIN, IN_SEL, DM, DF[1:0],
DP[1:0], PLL_BP, DA[1:0], DB[1:0], DC[1:0],
QA_CTRL1, QA_CTRL2, QB_CTRL,
QC_CTRL, QCC0.3V to (VCC + 0.3V)
Voltage Range at DIN, DIN (VCC - 2.35V) to (VCC - 0.35V)
Voltage Range at QA[4:0], QA[4:0], QB[2:0],
QB[2:0], QC, QC when LVDS Output0.3V to (VCC + 0.3V)

Current into QA[4:0], QA[4:0], QB[2:0], QE	
QC, QC when LVPECL Output	56mA
Current into QCC	±50mA
Voltage Range at XIN	0.3V to +1.2V
Voltage Range at XOUT	-0.3V to (VCC - 0.6V)
Continuous Power Dissipation (TA = +70°C	C)
48-Pin TQFN (derate 40mW/°C above +	70°C)3200mW
Operating Junction Temperature Range	55°C to +150°C
Storage Temperature Range	65°C to +160°C

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

#### **ELECTRICAL CHARACTERISTICS**

 $(V_{CC} = +3.0 \text{V to } +3.6 \text{V}, T_A = -40 ^{\circ}\text{C} \text{ to } +85 ^{\circ}\text{C}. \text{ Typical values are at } V_{CC} = +3.3 \text{V}, T_A = +25 ^{\circ}\text{C}, \text{ unless otherwise noted. Signal applied to CIN or DIN/DIN only when selected as the reference clock.) (Note 1)$ 

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	
Supply Current with PLL	1	Configured with LVPECL outputs		170	215	A	
Enabled (Note 2)	Icc	Configured with LVDS outputs		290	365	mA	
Supply Current with PLL		Configured with LVPECL outputs		110		то Л	
Bypassed (Note 2)		Configured with LVDS outputs		230		mA	
LVCMOS/LVTTL CONTROL INF QA_CTRL2, QB_CTRL, QC_CT		_, DM, DF[1:0], DA[1:0], DB[1:0], DC[1:0], P	LL_BP, D	P[1:0], Q	A_CTRL	1,	
Input High Voltage	VIH		2.0			V	
Input Low Voltage	VIL				0.8	V	
Input High Current	Iн	VIN = VCC			80	μΑ	
Input Low Current	IIL	VIN = 0V	-80			μΑ	
LVCMOS/LVTTL CLOCK INPUT	(CIN)						
Reference Clock Input Frequency	fREF		15		160	MHz	
Input Amplitude Range		Internally AC-coupled (Note 3)	1.2		3.6	VP-P	
Input High Current	IIH	VIN = VCC			80	μA	
Input Low Current	IIL	V <sub>IN</sub> = 0V	-80			μΑ	
Reference Clock Input Duty Cycle			40		60	%	
Input Capacitance				1.5		pF	
DIFFERENTIAL CLOCK INPUT	(DIN, DIN) (N	ote 4)					
Differential Input Frequency	fREF		15		350	MHz	
Input Bias Voltage	VCMI		VCC -	VCC -		V	
Input Differential Voltage Swing			150		1800	mV <sub>P-P</sub>	
Single-Ended Voltage Range			VCC - 2.0		V <sub>CC</sub> - 0.7	V	
Input Differential Impedance			80	100	120	Ω	
Differential Input Capacitance				1.5		pF	

### **ELECTRICAL CHARACTERISTICS (continued)**

(VCC = +3.0V to +3.6V, TA = -40°C to +85°C. Typical values are at VCC = +3.3V, TA = +25°C, unless otherwise noted. Signal applied to CIN or DIN/ $\overline{\text{DIN}}$  only when selected as the reference clock.) (Note 1)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
LVDS OUTPUTS (QA[4:0], QA[4	:0], QB[2:0],	<b>QB</b> [2:0], QC, <b>QC</b> ) (Note 5)				
Output Frequency					800	MHz
Output High Voltage	Voh				1.475	V
Output Low Voltage	VoL		0.925			V
Differential Output Voltage	IV <sub>OD</sub> I		250		400	mV
Change in Magnitude of Differential Output for Complementary States	ΔIVODI				25	mV
Output Offset Voltage	Vos		1.125		1.3	V
Change in Magnitude of Output Offset Voltage for Complementary States	ΔIV <sub>OS</sub> I				25	mV
Differential Output Impedance			80	100	140	Ω
0.1.101		Short together		3		
Output Current		Short to ground		6		mA mA
Output Current When Disabled		$V_{Q} = V_{\overline{Q}} = 0V \text{ to } V_{CC}$		10		μA
Output Rise/Fall Time		20% to 80%		160	240	ps
Output Duty-Cycle Distortion		PLL enabled PLL bypassed (Note 6)	48	50 50	52	%
LVPECL OUTPUTS (QA[4:0], Q	Δ[4·0] OB[2·					
Output Frequency	<u> </u>				800	MHz
Output High Voltage	VoH		V <sub>CC</sub> -	VCC - 0.98	V <sub>CC</sub> - 0.83	V
Output Low Voltage	V <sub>OL</sub>		V <sub>C</sub> C - 1.85	V <sub>C</sub> C - 1.70	V <sub>C</sub> C - 1.55	V
Output-Voltage Swing (Single-Ended)			0.5	0.7	0.9	V <sub>P-P</sub>
Output Current When Disabled		$VQ_{-} = V\overline{Q_{-}} = 0V \text{ to VCC}$		10		μΑ
Output Rise/Fall Time		20% to 80%		140	240	ps
Output Duty Ovala Distartian		PLL enabled	48	50	52	0/
Output Duty-Cycle Distortion		PLL bypassed (Note 6)		50		%
LVCMOS/LVTTL OUTPUT (QCC	;)					
Output Frequency					160	MHz
Output High Voltage		I <sub>OH</sub> = -12mA	2.6		Vcc	V
Output Low Voltage		IOL = 12mA			0.4	V
Output Rise/Fall Time		20% to 80% (Note 8)	150	400	850	ps
Outside Data Out   District		PLL enabled	42	50	58	01
Output Duty-Cycle Distortion		PLL bypassed (Note 6)		50		%
Output Impedance				15		Ω

PARAMETER	SYMBOL	CO	ONDITIONS	MIN	TYP	MAX	UNITS	
PLL SPECIFICATIONS				1				
V00 F		Low VCO (DP1 =	= 0 or NC)	3600	3750	3830		
VCO Frequency Range	fvco	High VCO (DP1	= 1)	3830	3932	4025	MHz	
Phase-Frequency Detector Compare Frequency	fPFD			15		42	MHz	
PLL Jitter Transfer Bandwidth					130		kHz	
		25MHz crystal	12kHz to 20MHz		0.34	1.0		
Integrated Dhoop litter	RJ	input (Note 9)	1.875MHz to 20MHz		0.14		2 200.46	
Integrated Phase Jitter	MJ	25MHz LVCMOS (Notes 9, 10)	or differential input		0.34		psrms	
Supply-Noise Induced Phase Spur at LVPECL/LVDS Output		(Note 11)			-56		dBc	
Supply-Noise Induced Phase Spur at LVCMOS Output		(Note 11)			-45		dBc	
Determinisitic Jitter Induced by Power-Supply Noise		LVPECL or LVDS (Note 11)			6		psp-p	
Nonharmonic and Subharmonic Spurs		(Note 12)			-70		dBc	
		foffset = 1kHz	foffset = 1kHz		-111			
		foffset = 10kHz	2	-113		dBc/		
SSB Phase Noise at 491.52MHz		foffset = 100kH	łz		-119		Hz	
		foffset = 1MHz			-136			
		foffset ≥ 10MH:	Z		-147			
		foffset = 1kHz			-115			
		foffset = 10kHz			-116		dD-1	
SSB Phase Noise at 312.5MHz		foffset = 100kH	łz	-122		dBc/ Hz		
		foffset = 1MHz			-139			
		foffset ≥ 10MH:	Z		-149			
		foffset = 1kHz			-117			
SSB Phase Noise at 245.76MHz		fOFFSET = 10kHz -119			dBc/			
		foffset = 100kH	łz		-125		Hz	
		foffset = 1MHz			-142		1	
		foffset ≥ 10MH:	Z		-151	_		
		foffset = 1kHz			-122		_	
		foffset = 10kHz			-123		dBc/	
SSB Phase Noise at 156.25MHz		foffset = 100kH			-129		Hz	
		foffset = 1MHz			-145		4	
		foffset ≥ 10MH	Z		-152			

#### **ELECTRICAL CHARACTERISTICS (continued)**

 $(VCC = +3.0V \text{ to } +3.6V, TA = -40^{\circ}\text{C} \text{ to } +85^{\circ}\text{C}. \text{ Typical values are at } VCC = +3.3V, TA = +25^{\circ}\text{C}, \text{ unless otherwise noted. Signal applied to CIN or DIN/\overline{DIN} only when selected as the reference clock.) (Note 1)$ 

PARAMETER	SYMBOL	CONDITIONS MIN TYP MA		MAX	UNITS		
		fOFFSET = 1kHz		-123			
		foffset = 10kHz		-124		-10-/	
SSB Phase Noise at 125MHz		foffset = 100kHz		-130		dBc/ Hz	
		foffset = 1MHz		-147		112	
		fOFFSET ≥ 10MHz		-153			
SSB Phase Noise at 100MHz		foffset = 1kHz		-126			
		foffset = 10kHz		-127		JD. /	
		foffset = 100kHz		-133		dBc/ Hz	
		foffset = 1MHz		-148		] ''2	
		foffset ≥ 10MHz		-152			

- **Note 1:** A series resistor of up to  $10.5\Omega$  is allowed between V<sub>CC</sub> and V<sub>CCA</sub> for filtering supply noise when system power-supply tolerance is V<sub>CC</sub> =  $3.3V \pm 5\%$ . See Figure 3.
- Note 2: Measured with all outputs enabled and unloaded.
- Note 3: CIN can be AC- or DC-coupled. See Figure 8. Input high voltage must be ≤ VCC + 0.3V.
- Note 4: DIN can be AC- or DC-coupled. See Figure 10.
- **Note 5:** Measured with  $100\Omega$  differential load.
- Note 6: Measured with crystal input, or with 50% duty cycle LVCMOS or differential input.
- **Note 7:** Measured with output termination of  $50\Omega$  to VCC 2V or Thevenin equivalent.
- **Note 8:** Measured with a series resistor of  $33\Omega$  to a load capacitance of 3.0pF. See Figure 1.
- Note 9: Measured at 156.25MHz.
- **Note 10:** Measured using LVCMOS/LVTTL input with slew rate ≥ 1.0V/ns, or differential input with slew rate ≥ 0.5V/ns.
- Note 11: Measured at 156.25MHz output with 200kHz, 50mVp.p sinusoidal signal on the supply using the crystal input and the power-supply filter shown in Figure 3. See the *Typical Operating Characteristics* for other supply noise frequencies. Deterministic jitter is calculated from the measured power-supply-induced spurs. For more information, refer to Application Note 4461: *HFAN-04.5.5*: Characterizing Power-Supply Noise Rejection in PLL Clock Synthesizers.
- Note 12: Measured with all outputs enabled and all three banks at different frequencies.

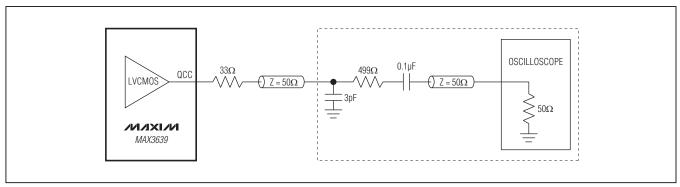
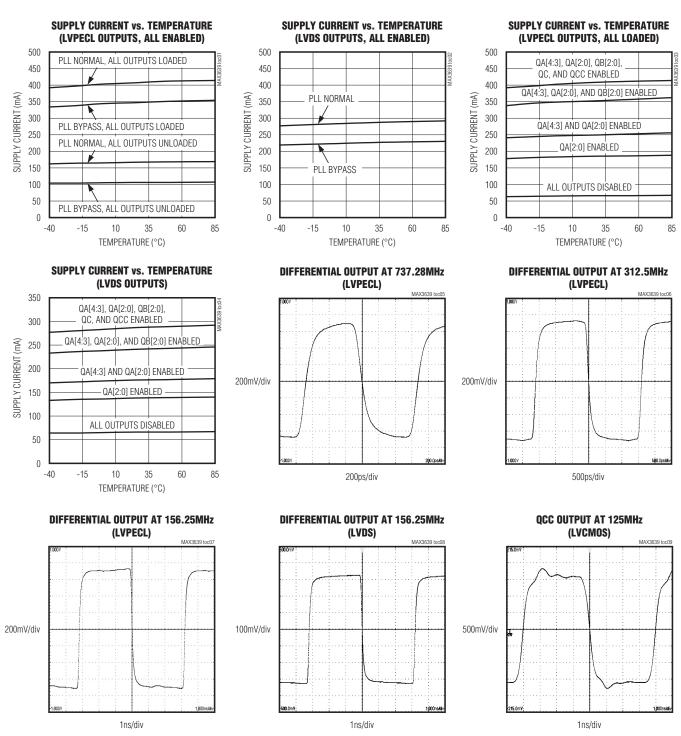


Figure 1. LVCMOS Output Measurement Setup

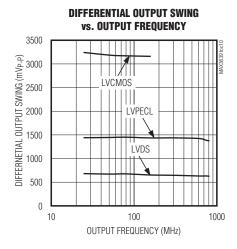
## **Typical Operating Characteristics**

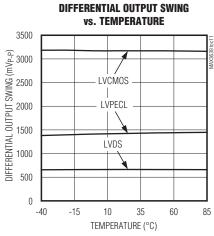
 $(V_{CC} = 3.3V, T_A = +25^{\circ}C, unless otherwise noted.)$ 

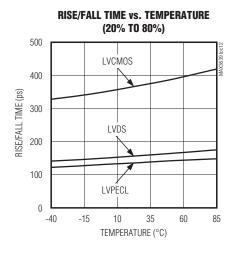


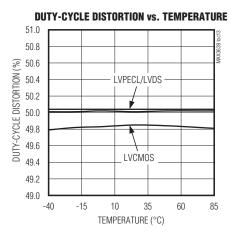
## Typical Operating Characteristics (continued)

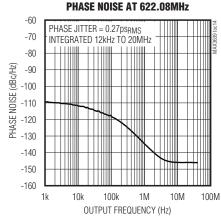
(V<sub>CC</sub> = 3.3V, T<sub>A</sub> = +25°C, unless otherwise noted.)

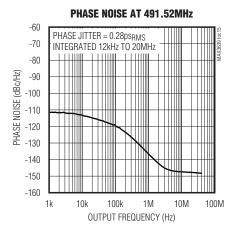


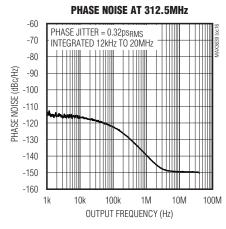


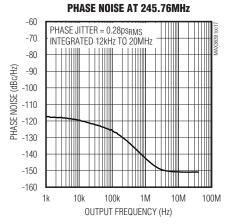


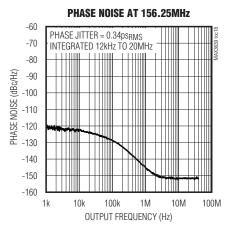






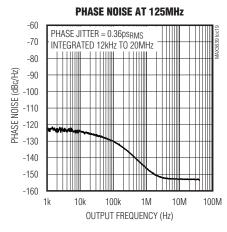


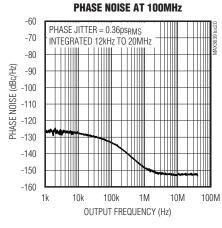


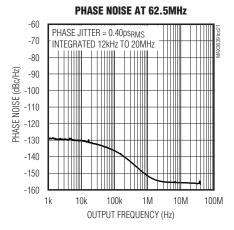


## Typical Operating Characteristics (continued)

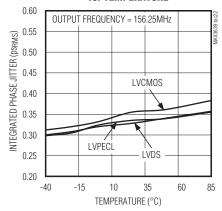
(VCC = 3.3V, TA = +25°C, unless otherwise noted.)

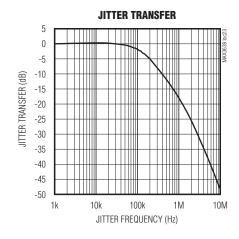




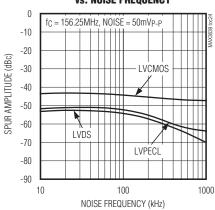


## INTEGRATED PHASE JITTER (12kHz TO 20MHz) vs. Temperature

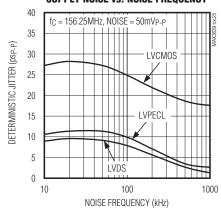




## SPURS INDUCED BY POWER-SUPPLY NOISE vs. Noise Frequency



## DETERMINISTIC JITTER INDUCED BY POWER SUPPLY NOISE vs. NOISE FREQUENCY



## Pin Description

PIN	NAME	FUNCTION	
1	DM	LVCMOS/LVTTL Input. Three-level control for input divider M. See Table 3.	
2	XIN	Crystal Oscillator Input	
3	XOUT	Crystal Oscillator Output	
4	Vcc	Core Power Supply. Connect to +3.3V.	
5	IN_SEL	LVCMOS/LVTTL Input. Three-level control for input mux. See Table 1.	
6	PLL_BP	LVCMOS/LVTTL Input. Three-level control for PLL bypass mode. See Table 2.	
7, 8	DF1, DF0	LVCMOS/LVTTL Inputs. Three-level controls for feedback divider F. See Table 4.	
9	QC_CTRL	LVCMOS/LVTTL Input. Three-level control input for C-bank output interface. See Table 10.	
10	VCCA	Power Supply for Internal Voltage-Controlled Oscillators (VCOs). See Figure 3.	
11, 12	DP1, DP0	LVCMOS/LVTTL Inputs. Three-level controls for VCO select and prescale divider P. See Table 7.	
13, 14	DB1, DB0	LVCMOS/LVTTL Inputs. Three-level controls for output divider B. See Table 5.	
15, 16	DA1, DA0	LVCMOS/LVTTL Inputs. Three-level controls for output divider A. See Table 5.	
17, 18	DC1, DC0	LVCMOS/LVTTL Inputs. Three-level controls for output divider C. See Table 6.	
19	QA_CTRL2	LVCMOS/LVTTL Input. Three-level control for QA[4:3] output interface. See Table 8.	
20	Vccqcc	Power Supply for QCC Output. Connect to +3.3V.	
21	QCC	C-Bank LVCMOS Clock Output	
22, 23	QC, QC	C-Bank Differential Output. Configured as LVPECL or LVDS with the QC_CTRL pin.	
24	Vccqc	Power Supply for C-Bank Differential Output. Connect to +3.3V.	
25, 36	VCCQA	Power Supply for A-Bank Differential Outputs. Connect to +3.3V.	
26, 27	QA4, QA4	A-Bank Differential Output. Configured as LVPECL or LVDS with the QA_CTRL2 pin.	
28, 29	QA3, QA3	A-Bank Differential Output. Configured as LVPECL or LVDS with the QA_CTRL2 pin.	
30, 31	QA2, QA2	A-Bank Differential Output. Configured as LVPECL or LVDS with the QA_CTRL1 pin.	
32, 33	QA1, QA1	A-Bank Differential Output. Configured as LVPECL or LVDS with the QA_CTRL1 pin.	
34, 35	QAO, QAO	A-Bank Differential Output. Configured as LVPECL or LVDS with the QA_CTRL1 pin.	
37	VCCQB	Power Supply for B-Bank Differential Outputs. Connect to +3.3V.	
38, 39	QB0, QB0	B-Bank Differential Output. Configured as LVPECL or LVDS with the QB_CTRL pin.	
40, 41	QB1, QB1	B-Bank Differential Output. Configured as LVPECL or LVDS with the QB_CTRL pin.	
42, 43	QB2, QB2	B-Bank Differential Output. Configured as LVPECL or LVDS with the QB_CTRL pin.	
44	QA_CTRL1	LVCMOS/LVTTL Input. Three-level control for QA[2:0] output interface. See Table 8.	
45	QB_CTRL	LVCMOS/LVTTL Input. Three-level control for B-bank output interface. See Table 9.	
46, 47	DIN, DIN	Differential Clock Input. Operates up to 350MHz. This input can accept DC-coupled LVPECL signals, and is internally biased to accept AC-coupled LVDS, CML, and LVPECL signals.	
48	CIN	LVCMOS Clock Input. Operates up to 160MHz.	
_	EP	Exposed Pad. Connect to supply ground for proper electrical and thermal performance.	

### **Detailed Description**

The MAX3639 is a low-jitter clock generator designed to operate over a wide range of frequencies. It consists of a selectable reference clock (on-chip crystal oscillator, LVCMOS input, or differential input), PLL with on-chip VCO, pin-programmable dividers and muxes, and three

banks of clock outputs. See Figure 2. The output banks include nine pin-programmable LVDS/LVPECL output buffers and one LVCMOS output buffer. The frequency, enabling, and output interface of each output bank can be individually programmed. In addition the A-bank is split into two banks with programmable enabling and

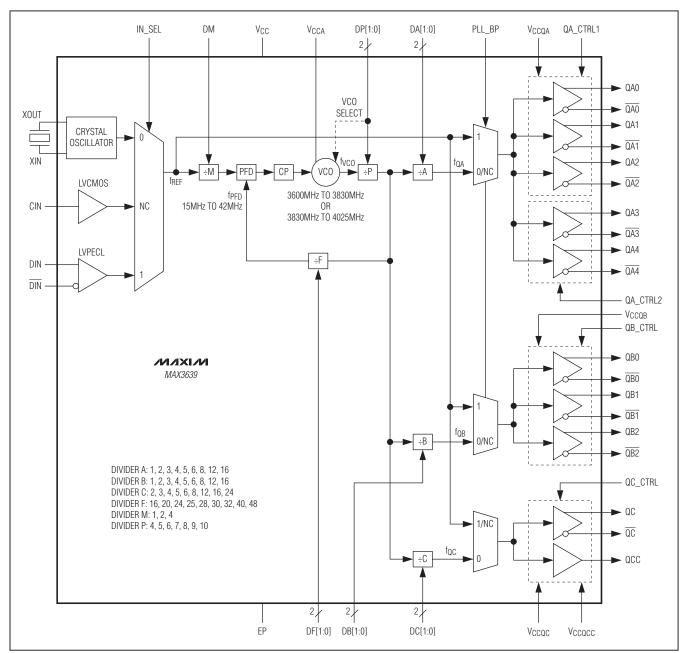


Figure 2. Detailed Functional Diagram

output interface. A PLL bypass mode is also available for system testing or clock distribution.

#### **Crystal Oscillator**

The on-chip crystal oscillator provides the low-frequency reference clock for the PLL. This oscillator requires an external crystal connected between XIN and XOUT. See the *Crystal Selection and Layout* section for more information. The XIN and XOUT pins can be left open if not used.

#### **LVCMOS Clock Input**

An LVCMOS-compatible clock source can be connected to CIN to serve as the PLL reference clock. The input is internally biased to allow AC- or DC-coupling (see the *Applications Information* section). It is designed to operate from 15MHz to 160MHz. No signal should be applied to CIN if not used.

#### **Differential Clock Input**

A differential clock source can be connected to DIN to serve as the PLL reference clock. This input operates from 15MHz to 350MHz and contains an internal  $100\Omega$  differential termination. This input can accept DC-coupled LVPECL signals, and is internally biased to accept AC-coupled LVDS, CML, and LVPECL signals

(see the *Applications Information* section). No signal should be applied to DIN if not used.

#### Phase-Locked Loop (PLL)

The PLL takes the signal from the crystal oscillator, LVCMOS clock input, or differential clock input and synthesizes a low-jitter, high-frequency clock. The PLL contains a phase-frequency detector (PFD), a charge pump (CP), and two low phase noise VCOs that combined give a wide 3.60GHz to 4.025GHz frequency range. The high-frequency VCO output is divided by prescale divider P and then is connected to the PFD input through a feedback divider F. The PFD compares the reference frequency to the divided-down VCO output and generates a control signal that keeps the VCO locked to the reference clock. The high-frequency VCO/P output clock is sent to the output dividers. To minimize noise-induced jitter, the VCO supply (VCCA) is isolated from the core logic and output buffer supplies.

#### **Dividers and Muxes**

The dividers and muxes are set with three-level control inputs. Divider settings and routing information are given in Tables 1 to 7. See Table 11 for example divider configurations used in various applications.

#### Table 1. PLL Input

IN_SEL	INPUT
0	Crystal Input. XO circuit is disabled when not selected.
1	Differential Input. No signal should be applied to DIN if not selected
NC	LVCMOS Input. No signal should be applied to CIN if not selected.

#### Table 2. PLL Bypass

PLL_BP	PLL OPERATION
0	PLL Enabled for Normal Operation. All outputs from the A, B, and C banks are derived from the VCO.
1	PLL Bypassed. Selected input passes directly to the outputs. Both VCOs are disabled to minimize power consumption and intermodulation spurs. Used for system testing or clock distribution.
NC	The outputs from A-bank and B-bank are derived from the VCO, but the C-bank outputs are directly driven from the input signal for purposes of daisy chaining.

### Table 3. Input Divider M

DM	M DIVIDER RATIO			
0	÷1			
1	÷2			
NC	÷4			

**Note:** When the on-chip XO is selected (IN\_SEL = 0), the setting DM = 0 is required.

Table 4. PLL Feedback Divider F

DF1	DF0	F DIVIDER RATIO
0	0	÷25
0	1	÷20
1	0	÷16
1	1	÷32
1	NC	÷24
NC	1	÷30
0	NC	÷40
NC	0	÷48
NC	NC	÷28

Table 5. Output Divider A, B

DA1/DB1	DA0/DB0	A, B DIVIDER RATIO
0	0	÷2
0	1	÷3
1	0	÷4
1	1	÷5
1	NC	÷6
NC	1	÷8
0	NC	÷12
NC	0	÷16
NC	NC	÷1

#### Table 6. Output Divider C

DC1	DC0	C DIVIDER RATIO
0	0	÷2
0	1	÷3
1	0	÷4
1	1	÷5
1	NC	÷6
NC	1	÷8
0	NC	÷12
NC	0	÷16
NC	NC	÷24

#### Table 7. VCO Select and Prescale Divider P

DP1	DP0	VCO FREQUENCY RANGE (MHz)	P DIVIDER RATIO	(VCO/P) FREQUENCY RANGE (MHz)
	0	Low	÷5	720 to 766
0	1	(3600 to	÷6	600 to 638.33
	NC	3830)	÷9	400 to 425.50
	0		÷7	547.14 to 575
NC	1		÷10	383 to 402.50
	NC	High	÷8	478.75 to 503.12
	0	(3830 to 4025)	÷4	957.50 to 1006.25
1	1		÷5	766 to 805
	NC		÷6	638.33 to 670.83

### **Table 8. A-Bank Output Interface**

QA_CTRL1	QA[2:0] OUTPUT
0	QA[2:0] = LVDS
1	QA[2:0] = LVPECL
NC	QA[2:0] disabled to high impedance
QA_CTRL2	QA[4:3] OUTPUT
0	QA[4:3] = LVDS
1	QA[4:3] = LVPECL
NC	QA[4:3] disabled to high impedance

#### Table 9. B-Bank Output Interface

QB_CTRL	QB[2:0] OUTPUT			
0	QB[2:0] = LVDS			
1	QB[2:0] = LVPECL			
NC	QB[2:0] disabled to high impedance			

#### **Table 10. C-Bank Output Interface**

QC_CTRL	QC AND QCC OUTPUT
0	QC = LVDS, QCC = LVCMOS
1	QC = LVPECL, QCC = LVCMOS
NC	QC and QCC disabled to high impedance

#### **LVDS/LVPECL Clock Outputs**

The differential clock outputs (QA[4:0], QB[2:0], QC) operate up to 800MHz and have a pin-programmable LVDS/LVPECL output interface. See Tables 8 to 10. When configured as LVDS, the buffers are designed to drive transmission lines with a  $100\Omega$  differential

termination. When configured as LVPECL, the buffers are designed to drive transmission lines terminated with  $50\Omega$  to VCC - 2V. Unused output banks can be disabled to high impedance and unused outputs can be left open.

#### **LVCMOS Clock Output**

The LVCMOS clock output operates up to 160MHz and is designed to drive a single-ended high-impedance load. If unused, this output can be left open or the C-bank can be disabled to high impedance.

#### **Internal Reset**

During power-on, a power-on reset (POR) signal is generated to synchronize all dividers. A reset signal is also generated if any control pin is changed. Outputs within a bank are phase aligned, but outputs bank-to-bank may not be phase aligned.

### **Applications Information**

#### **Output Frequency Configuration**

The MAX3639 output frequencies (fQA, fQB, fQC) are functions of the reference frequency (fREF) and the pin-programmable dividers (A, B, C, F, M). The relationships can be expressed as:

$$f_{QA} = \frac{f_{REF}}{M} \times \frac{F}{A}$$
 (1)

$$f_{QB} = \frac{f_{REF}}{M} \times \frac{F}{B}$$
 (2)

$$f_{QC} = \frac{f_{REF}}{M} \times \frac{F}{C}$$
 (3)

The frequency ranges for the selected reference clocks are 18MHz to 33.5MHz for the crystal oscillator input, 15MHz to 160MHz for the LVCMOS input, and 15MHz to 350MHz for the differential input. The available dividers are given in Tables 3 to 6.

For a given reference frequency fREF, the input divider M, the PLL feedback divider F, and VCO prescale divider P must be configured so the VCO frequency (fvco) falls within the specified ranges. Invalid PLL configuration leads to VCO frequencies beyond the specified ranges and can result in loss of lock. An expression for the VCO frequency along with the specified ranges is given by:

$$f_{VCO} = \frac{f_{REF}}{M} \times F \times P \qquad (4)$$

 $3600MHz \le f_{VCO} \le 3830MHz \text{ (when DP1 = 0)} (5)$ 

 $3830MHz \le f_{VCO} \le 4025MHz \text{ (when DP1 = 1 or NC) (6)}$ 

The prescale divider P is set by pins DP1 and DP0 as given in Table 7.

In addition, the reference clock frequency and input divider M must also be selected so the PFD compare frequency (fPFD) falls within the specified range of 15MHz to 42MHz. If applicable, the higher fPFD should be selected for optimal jitter performance.

$$f_{PFD} = \frac{f_{REF}}{M} = \frac{f_{VCO}}{P \times F}$$
 (7)

$$15MHz \le fppd \le 42MHz$$
 (8)

Note that the reference clock frequency is not limited by the fPFD range when the PLL is in bypass mode.

#### **Example Frequency Configuration**

The following is an example of how to find divider ratios for a valid PLL configuration, given a requirement of input and output frequencies.

1) Select input and output frequencies for an Ethernet application.

fREF = 25MHz

fQA = 312.5MHz

 $f_{QB} = 156.25MHz$ 

fQC = 125MHz

- 2) Find the input divider M for a valid PFD compare frequency. Using Table 3 and equations (7) and (8), it is determined that  $M = \div 1$  is the only valid option.
- 3) Find the feedback divider F and prescale divider P for a valid fvco. Using Tables 4 and 7 along with equations (4), (5), and (6), it is determined that F = ÷25 and P = ÷6 results in fvco = 3750MHz, which is within the valid range of the low VCO.
- 4) Find the output dividers A, B, C for the required output frequencies. Using Tables 5 and 6 and equations (1), (2), and (3), it is determined that A = ÷2 gives fQA = 312.5MHz, B = ÷4 gives fQB = 156.25MHz, and C = ÷5 gives fQC = 125MHz.

Table 11 provides input and output frequencies along with valid divider ratios for a variety of applications.

Table 11. Reference Frequencies and Divider Ratios for Various Applications

		•						
fREF (MHz)	INPUT DIVIDER (M)	PLL FEEDBACK DIVIDER (F)	VCO FREQUENCY (MHz)	VCO PRESCALE DIVIDER (P)	OUTPUT DIVIDER (A, B, C)	OUTPUT FREQUENCY (MHz)	APPLICATIONS	
45.00	,	40		5	1	737.28		
15.36	1	48		5	2	368.64		
00.70	_	0.4		5	3	245.76		
30.72	1	24	00004	5	4	184.32		
61.44	2	24	3686.4	5	6	122.88		
				5	8	92.16		
122.88	4	24		5	12	61.44		
				5	24	30.72		
15.36	1	40		6	1	614.4	Wireless Base Station:	
19.2	1	32		6	2	307.2	WCDMA, cdma2000 <sup>®</sup> ,	
30.72	1	20		6	3	204.8	LTE, TD_SCDMA,	
38.4	1	16	0000 4	6	4	153.6	WiMAX™, GSM	
61.44	2	20	3686.4	6	5	122.88		
76.8	2	16		6	6	102.4		
122.88	4	20		6	8	76.8		
153.6	4	16		6	12	51.2		
30.72	1	32		4 (8)	2 (1)	491.52		
61.44	2	32	000040	4 (8)	4 (2)	245.76		
400.00		00	3932.16	4 (8)	8 (4)	122.88		
122.88	4	32		4 (8)	16 (8)	61.44	1	
13	1	32		9	1	416		
26	1	16	0744	9	4	104	0014	
	0	40	3744	9	8	52	GSM	
52	2	16		9	16	26		
25/31.25/ 62.5/125/	1/1/2/4/4	25/20/20/		6	1	625		
156.25	1/1/2/-/-	20/16	3750	6	2	312.5	- Ethernet	
26.04166	1	24	0.00	6	4	156.25	-	
				6	5	125		
				5	3	250		
25/31.25/	25/31 25/	1/1/2/4 30/24/24/24 3750			5	4	187.5	
62.5/125	1/1/2/4		5	5	150	Ethernet		
32.0/120				5	6	125		
			5	12	62.5			

cdma2000 is a registered trademark of the Telecommunications Industry Association. WiMAX is a trademark of WiMAX Forum.

Table 11. Reference Frequencies and Divider Ratios for Various Applications (continued)

fREF (MHz)	INPUT DIVIDER (M)	PLL FEEDBACK DIVIDER (F)	VCO FREQUENCY (MHz)	VCO PRESCALE DIVIDER (P)	OUTPUT DIVIDER (A, B, C)	OUTPUT FREQUENCY (MHz)	APPLICATIONS					
				6	2	318.75						
				6	3	212.5						
26.5625	1	24	3825	6	4	159.375	FC-SAN					
				6	6	106.25						
				6	12	53.125						
19.44	1	32		6	1	622.08						
38.88	1	16		6	2	311.04						
			3732.48	6	4	155.52	SONET/SDH, STM-N					
155.52	4	16		6	8	77.76						
				6	16	38.88						
33.3/66.7/ 133.3	1/2/4	24		5	2	400						
				5	3	266.67	Server, FB-DIMM,					
				5	4	200	Network Processor,					
05/50/400	1/0/4	32	4000	5	6	133.333	DDR/QDR Memory,					
25/50/100	1/2/4			5	5 8 10	100	PCIe, SATA					
				5	12	66.67						
											5	16
33.3/66.7/ 133.3	1/2/4	30		4	2	500						
25/50/100	1/2/4/8	40		4	3	333.33	Server, FB-DIMM,					
			4000	4	4	250	Processor Clock and					
31.25/		0.0		4	5	200	DDR/QDR Memory, PCIe, SATA					
62.5/125	·   1/1/1/1	32		4	6	166.67	TOIC, SATA					
				4	8	125						
00.70	,	0.4	0004.0	5	6	131.04	N					
32.76	1	24	3931.2	5	12	65.52	Microwave Radio Link					
20.82857		32		6	1	666.514						
44.0574	1	10	3999.084	6	2	333.257	OTU1, 10Gbps SONET					
41.6571	16		6	4	166.6285	with FEC						
05 70405	25.78125 1	25	0007.1075	6	1	644.53125	10Gbps Ethernet with					
25.78125			3867.1875	6	4	161.1328125	FEC '					
07.000570	20570	0.4		6	1	657.421875	1005 50					
27.392578	1	24	3944.53125	6	4	164.355	10Gbps FC					
20.916	1	32		6	1	669.3265	07110 4001 00157					
41 0000	1.8329 1 16	40:		6	2	334.66	OTU2, 10Gbps SONET with Digital Wrapper					
41.0329				10		6	4	167.33	with Digital Wapper			

#### **Power-Supply Filtering**

The MAX3639 is a mixed analog/digital IC. The PLL contains analog circuitry susceptible to random noise. To take full advantage of on-board filtering and noise attenuation, in addition to excellent on-chip power-supply rejection, this part provides a separate power-supply pin, VCCA, for the VCO circuitry. Figure 3 illustrates the recommended power-supply filter network for VCCA. The purpose of this design technique is to ensure clean input power supply to the VCO circuitry and to improve the overall immunity to power-supply noise. This network requires that the power supply is  $\pm 3.3V \pm 5\%$ . Decoupling capacitors should be used on all other supply pins for best performance. All supply connections should be driven from the same source.

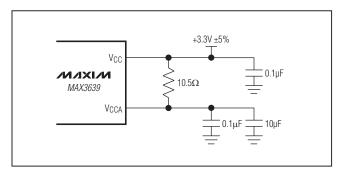


Figure 3. Power-Supply Filter

#### **Ground Connection**

The 48-pin TQFN package features an exposed pad (EP), which provides a low resistance thermal path for heat removal from the IC and also the electrical ground. For proper operation, the EP must be connected to the circuit board ground plane with multiple vias.

#### **Crystal Selection and Layout**

The MAX3639 features an integrated on-chip crystal oscillator to minimize system implementation cost. The crystal oscillator is designed to drive a fundamental mode, AT-cut crystal resonator. See Table 12 for recommended crystal specifications. See Figure 4 for the crystal equivalent circuit and Figure 5 for the recommended external capacitor connections. The crystal, trace, and two external capacitors should be placed on the board as close as possible to the XIN and XOUT pins to reduce crosstalk of active signals into the oscillator.

The total load capacitance for the crystal is a combination of external and on-chip capacitance. The layout shown in Figure 6 gives approximately 1.7pF of trace plus footprint capacitance per side of the crystal. Note the ground plane is removed under the crystal to minimize capacitance. There is approximately 2.5pF of on-chip capacitance between XIN and XOUT. With an external 27pF capacitor connected to XIN and a 33pF capacitor connected to XOUT, the total load capacitance for the crystal is approximately 18pF. The XIN and XOUT pins can be left open if not used.

**Table 12. Crystal Selection Parameters** 

-					
PARAMETER	SYMBOL	MIN	TYP	MAX	UNITS
Crystal Oscillation Frequency	fosc	18	25	33.5	MHz
Shunt Capacitance	C <sub>0</sub>		2.0	7.0	рF
Load Capacitance	CL		18		рF
Equivalent Series Resistance (ESR)	Rs		10	50	Ω
Maximum Crystal Drive Level				200	μW

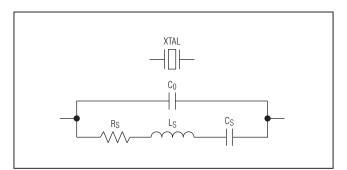


Figure 4. Crystal Equivalent Circuit

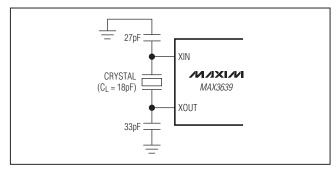


Figure 5. Crystal, Capacitor Connections

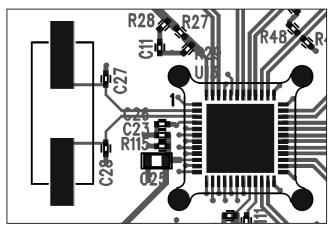


Figure 6. Crystal Layout

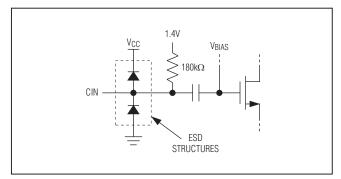


Figure 7. Equivalent CIN Circuit

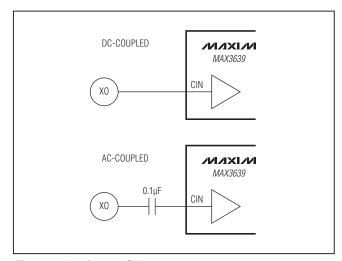


Figure 8. Interface to CIN

#### Interfacing with LVCMOS Input

The equivalent LVCMOS input circuit for CIN is given in Figure 7. This input is internally biased to allow AC- or DC-coupling, and has  $180 k\Omega$  input impedance. See Figure 8 for the interface circuit. No signal should be applied to CIN if not used.

#### Interfacing with Differential Input

The equivalent input circuit for DIN is given in Figure 9. This input operates up to 350MHz and contains an internal  $100\Omega$  differential termination as well as a  $35\Omega$  common-mode termination. The common-mode termination ensures good signal integrity when connected to a source with large common-mode signals. The input can accept DC-coupled LVPECL signals, and is internally biased to accept AC-coupled LVDS, CML, and LVPECL signals (Figure 10). No signal should be applied to DIN if not used.

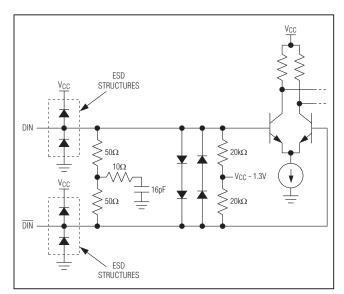


Figure 9. Equivalent DIN Circuit

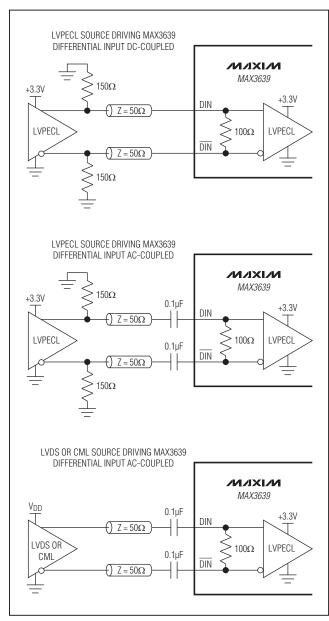


Figure 10. Interfacing to DIN

#### **Interfacing with LVPECL Outputs**

The equivalent LVPECL output circuit is given in Figure 11. These outputs are designed to drive a pair of  $50\Omega$  transmission lines terminated with  $50\Omega$  to V<sub>TT</sub> = V<sub>CC</sub> - 2V. If a separate termination voltage (V<sub>TT</sub>) is not available, other terminations methods can be used, as shown in Figure 12. For more information on LVPECL terminations and how to interface with other logic families, refer to Application Note 291: HFAN-01.0: Introduction to LVDS, PECL, and CML.

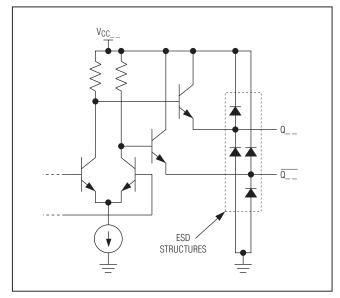


Figure 11. Equivalent LVPECL Output Circuit

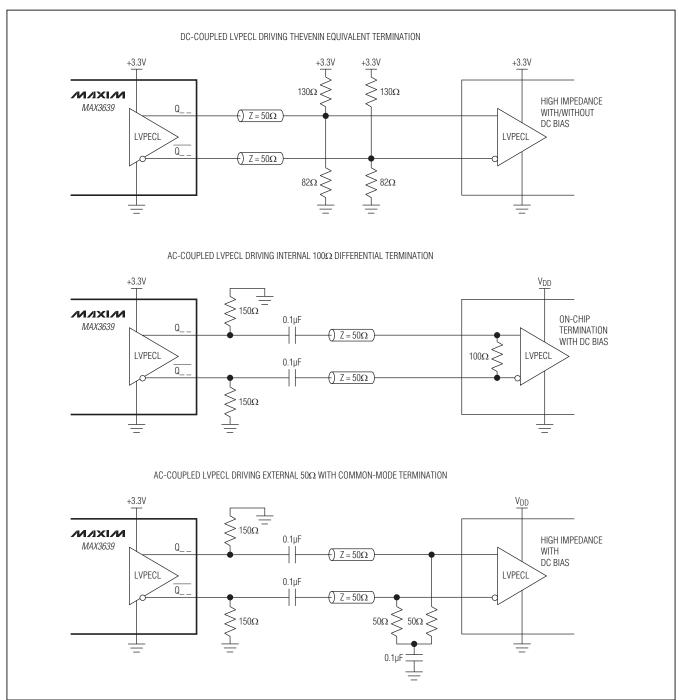


Figure 12. Interface to LVPECL Outputs

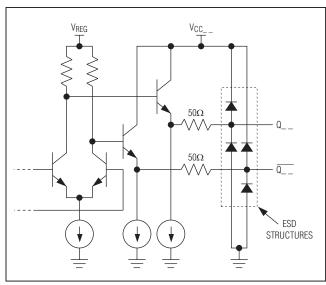


Figure 13. Equivalent LVDS Output Circuit

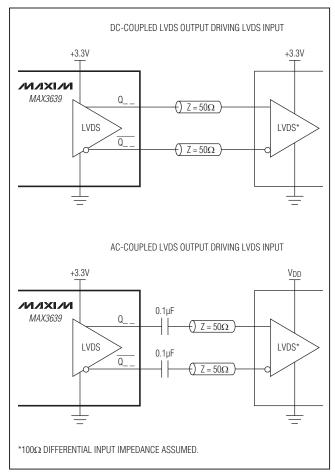


Figure 14. Interface to LVDS Outputs

#### **Interfacing with LVDS Outputs**

The equivalent LVDS output circuit is given in Figure 13. These outputs provide  $100\Omega$  differential output impedance designed to drive a  $100\Omega$  differential transmission line terminated with a  $100\Omega$  differential load. Example interface circuits are shown in Figure 14. For more information on LVDS terminations and how to interface with other logic families, refer to Application Note 291: *HFAN-01.0: Introduction to LVDS, PECL, and CML*.

#### **Interfacing with LVCMOS Output**

The equivalent LVCMOS output circuit is given in Figure 15. This output provides  $15\Omega$  output impedance and is designed to drive a high-impedance load. A series resistor of  $33\Omega$  is recommended at the LVCMOS output before the transmission line. An example interface circuit is shown in Figure 16.

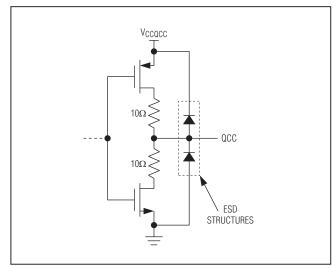


Figure 15. Equivalent LVCMOS Output Circuit

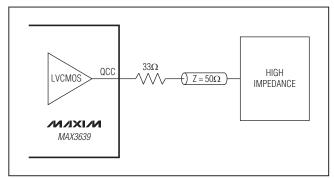


Figure 16. Interface to LVCMOS Output

#### **Layout Considerations**

The inputs and outputs are the most critical paths for the MAX3639; great care should be taken to minimize discontinuities on the transmission lines. Here are some suggestions for maximizing the performance of the MAX3639:

- An uninterrupted ground plane should be positioned beneath the clock outputs. The ground plane under the crystal should be removed to minimize capacitance.
- Supply decoupling capacitors should be placed close to the supply pins, preferably on the same side of the board as the MAX3639.
- Take care to isolate input traces from the MAX3639 outputs.

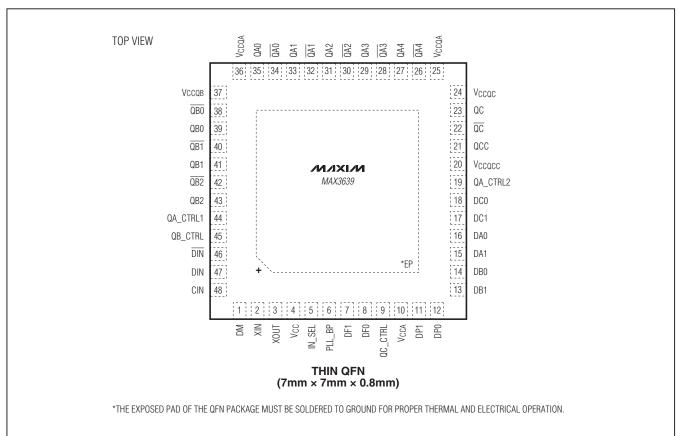
- The crystal, trace, and two external capacitors should be placed on the board as close as possible to the XIN and XOUT pins to reduce crosstalk of active signals into the oscillator.
- Maintain 100Ω differential (or 50Ω single-ended) transmission line impedance into and out of the part.
- Provide space between differential output pairs to reduce crosstalk, especially if the outputs are operating at different frequencies.
- Use multilayer boards with an uninterrupted ground plane to minimize EMI and crosstalk.

Refer to the MAX3639 evaluation kit for more information.

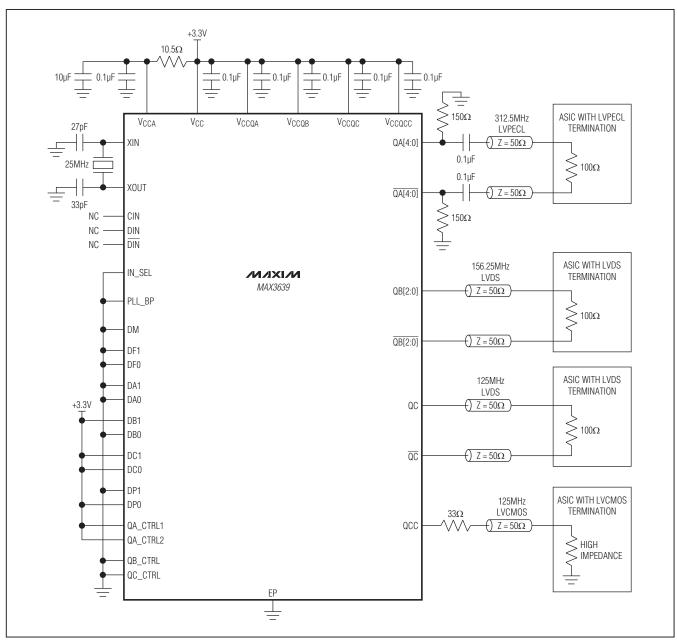
**Chip Information** 

PROCESS: BICMOS

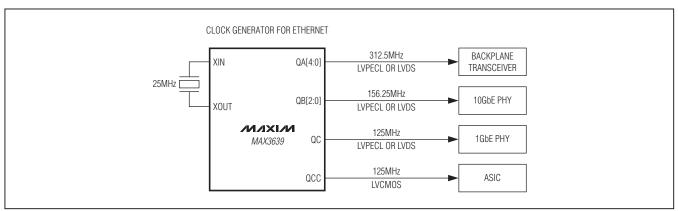
### Pin Configuration

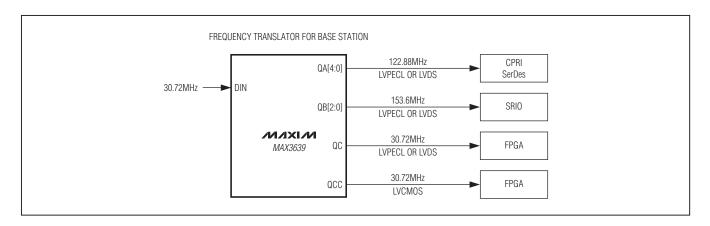


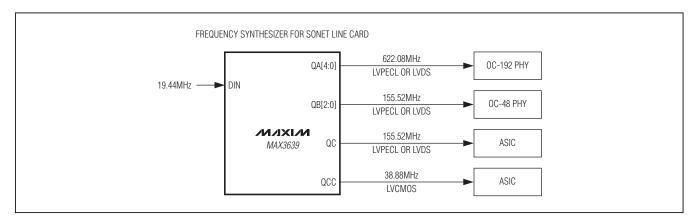
## **Typical Application Circuits**



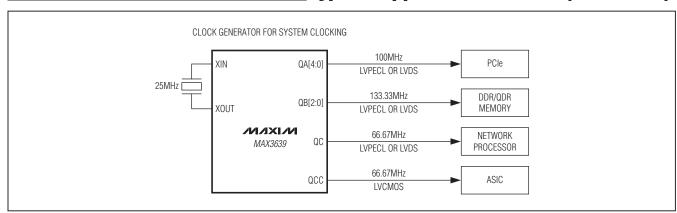
## **Typical Application Circuits (continued)**

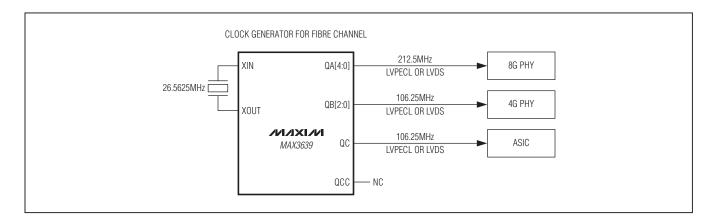






### **Typical Application Circuits (continued)**





#### **Package Information**

For the latest package outline information and land patterns, go to <a href="www.maxim-ic.com/packages">www.maxim-ic.com/packages</a>. Note that a "+", "#", or "-" in the package code indicates RoHS status only. Package drawings may show a different suffix character, but the drawing pertains to the package regardless of RoHS status.

PACKAGE TYPE	PACKAGE CODE	DOCUMENT NO.
48 TQFN-EP	T4877+4	<u>21-0144</u>

Maxim cannot assume responsibility for use of any circuitry other than circuitry entirely embodied in a Maxim product. No circuit patent licenses are implied. Maxim reserves the right to change the circuitry and specifications without notice at any time.